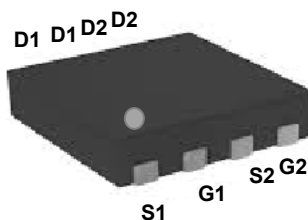
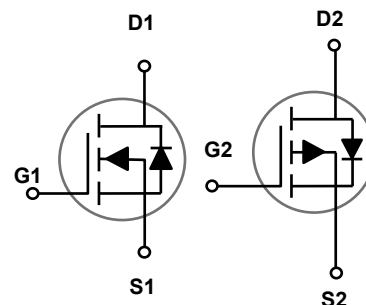


### Main Product Characteristics

Polarity	N-Ch	P-Ch
$V_{DSS}$	20V	-20V
$R_{DS(ON)(Max.)}$	40m $\Omega$	100m $\Omega$
$I_D$	3.8A	-2.5A



PPAK2X3 Dual Pin



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFN8116 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Rating		Unit
Drain-Source Voltage	$V_{DS}$	20	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	$\pm 10$	V
Drain Current – Continuous ( $T_C=25^{\circ}C$ )	$I_D$	3.8	-2.5	A
Drain Current – Continuous ( $T_C=100^{\circ}C$ )		2.3	-1.5	A
Drain Current – Pulsed <sup>1</sup>	$I_{DM}$	15.2	-10	A
Power Dissipation ( $T_C=25^{\circ}C$ )	$P_D$	1.25	1.25	W
Power Dissipation – Derate above 25 $^{\circ}C$		0.01	0.01	W/ $^{\circ}C$
Storage Temperature Range	$T_{STG}$	-55 to +150		$^{\circ}C$
Operating Junction Temperature Range	$T_J$	-55 to +150		$^{\circ}C$

### Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	100	$^{\circ}C/W$

### N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}, I_D=1\text{mA}$	---	0.02	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=3A$	---	30	40	m $\Omega$
		$V_{GS}=2.5V, I_D=2A$	---	42	55	m $\Omega$
		$V_{GS}=1.8V, I_D=1.5A$	---	55	70	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.6	1	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-2	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=2A$	---	4.4	---	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2, 3</sup>	$Q_g$	$V_{DS}=10V, V_{GS}=4.5V, I_D=3A$	---	5.8	10	nC
Gate-Source Charge <sup>2, 3</sup>	$Q_{gs}$		---	0.6	1.5	
Gate-Drain Charge <sup>2, 3</sup>	$Q_{gd}$		---	1.5	3	
Turn-On Delay Time <sup>2, 3</sup>	$T_{d(on)}$	$V_{DD}=10V, V_{GS}=4.5V, R_G=25\Omega, I_D=1A$	---	2.9	6	nS
Rise Time <sup>2, 3</sup>	$T_r$		---	8.4	16	
Turn-Off Delay Time <sup>2, 3</sup>	$T_{d(off)}$		---	19.2	38	
Fall Time <sup>2, 3</sup>	$T_f$		---	5.6	12	
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, F=1\text{MHz}$	---	315	600	pF
Output Capacitance	$C_{oss}$		---	50	80	
Reverse Transfer Capacitance	$C_{rss}$		---	40	60	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	---	---	3.8	A
Pulsed Source Current	$I_{SM}$		---	---	7.6	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

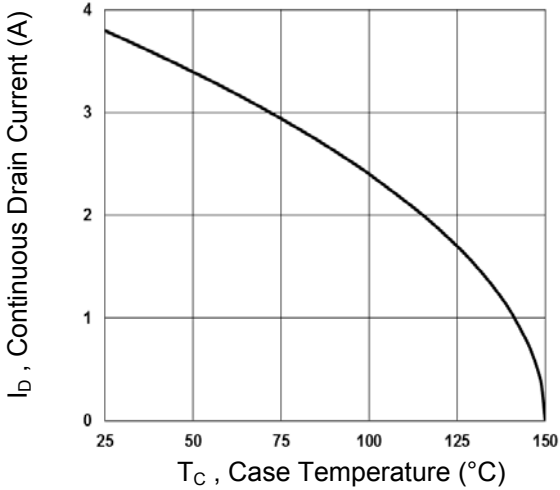
### P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.01	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-3A$	---	82	100	$\text{m}\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	---	125	140	$\text{m}\Omega$
		$V_{GS}=-1.8V, I_D=-1A$	---	197	230	$\text{m}\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.6	-1	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	3	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=-10V, I_D=-1A$	---	2.2	---	S
<b>Dynamic and switching Characteristics</b>						
Total Gate Charge <sup>2, 3</sup>	$Q_g$	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-2A$	---	4.8	10	nC
Gate-Source Charge <sup>2, 3</sup>	$Q_{gs}$		---	0.5	1	
Gate-Drain Charge <sup>2, 3</sup>	$Q_{gd}$		---	1.9	4	
Turn-On Delay Time <sup>2, 3</sup>	$T_{d(on)}$	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=25\Omega, I_D=-1A$	---	3.5	7	nS
Rise Time <sup>2, 3</sup>	$T_r$		---	12.6	24	
Turn-Off Delay Time <sup>2, 3</sup>	$T_{d(off)}$		---	32.6	62	
Fall Time <sup>2, 3</sup>	$T_f$		---	8.4	16	
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V, F=1\text{MHz}$	---	350	510	pF
Output Capacitance	$C_{oss}$		---	65	95	
Reverse Transfer Capacitance	$C_{rss}$		---	50	75	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	---	---	-2.5	A
Pulsed Source Current	$I_{SM}$		---	---	-5	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1	V

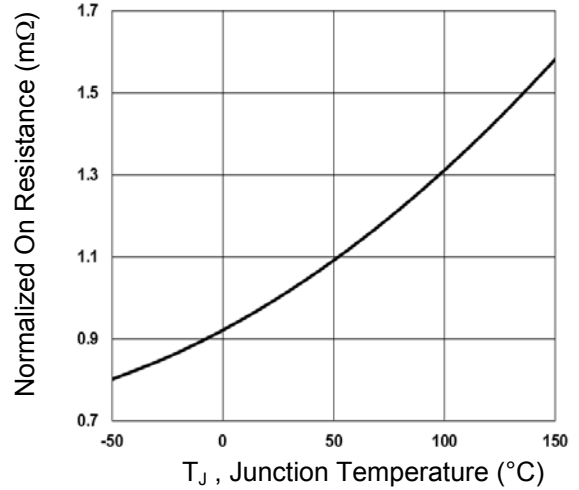
Note:

4. Repetitive Rating: Pulsed width limited by maximum junction temperature.
5. The data tested by pulsed, pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
6. Essentially independent of operating temperature.

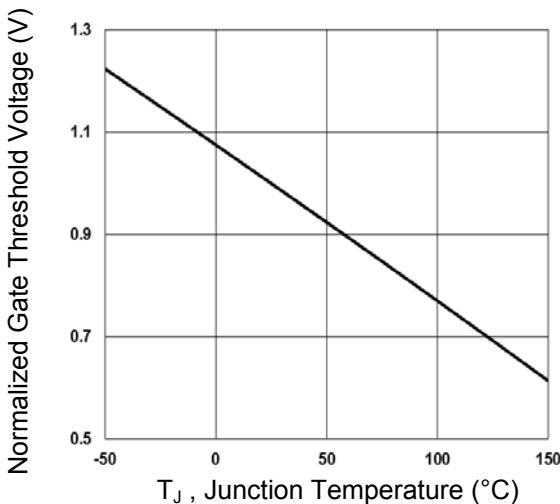
**N-Channel Typical Characteristic Curves**



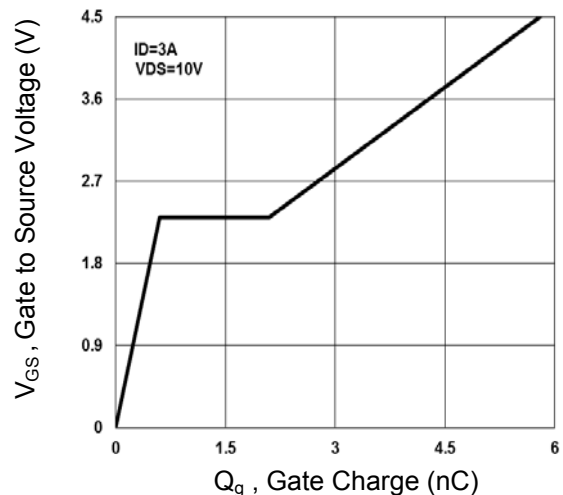
**Fig.1 Continuous Drain Current vs.  $T_C$**



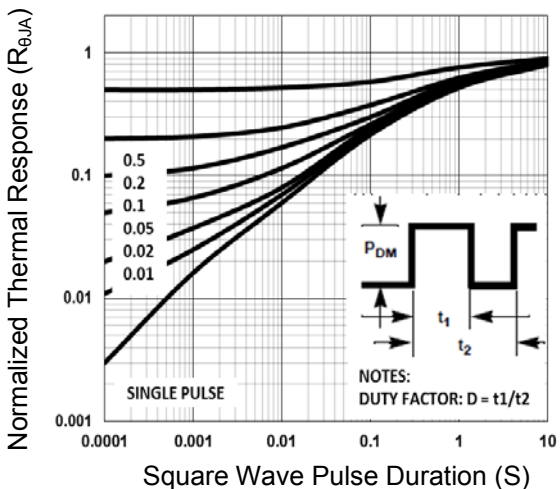
**Fig.2 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



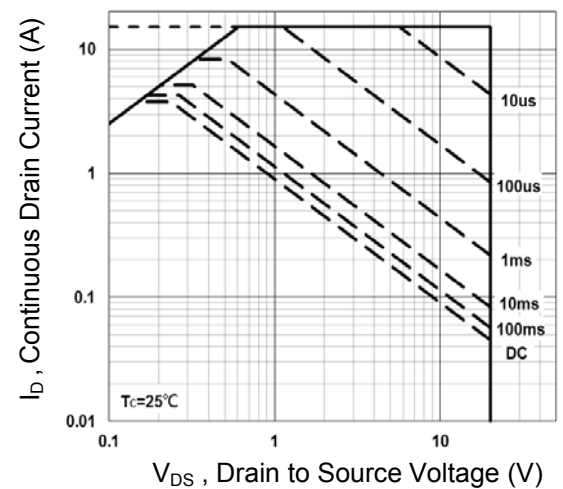
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Waveform**

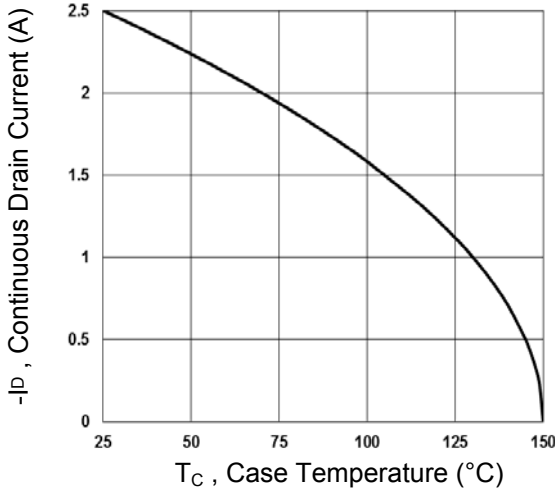


**Fig.5 Normalized Transient Impedance**

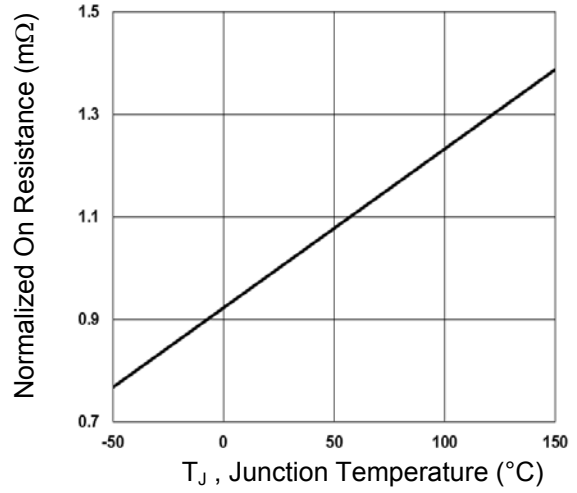


**Fig.6 Maximum Safe Operation Area**

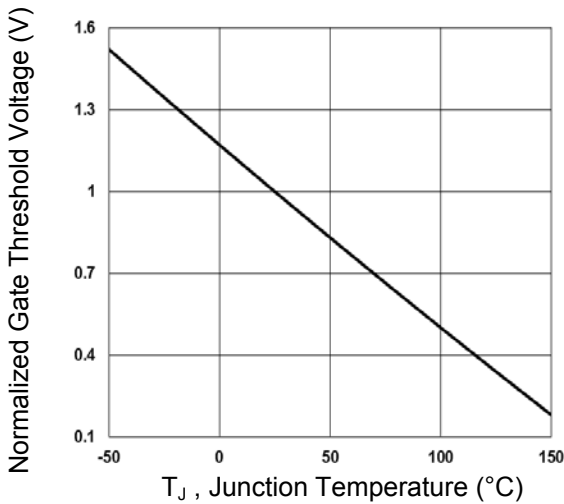
**P-Channel Typical Characteristic Curves**



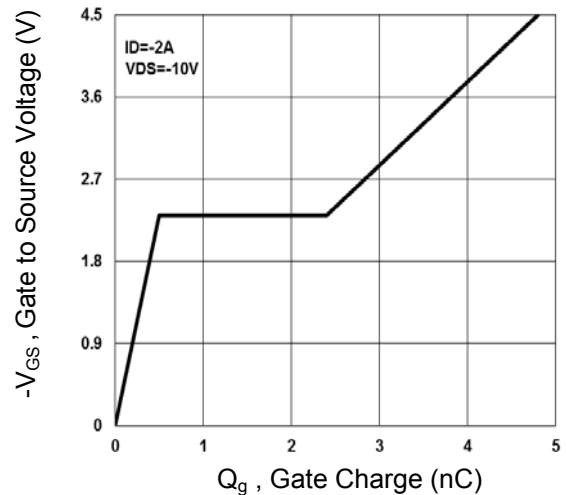
**Fig.7 Continuous Drain Current vs.  $T_C$**



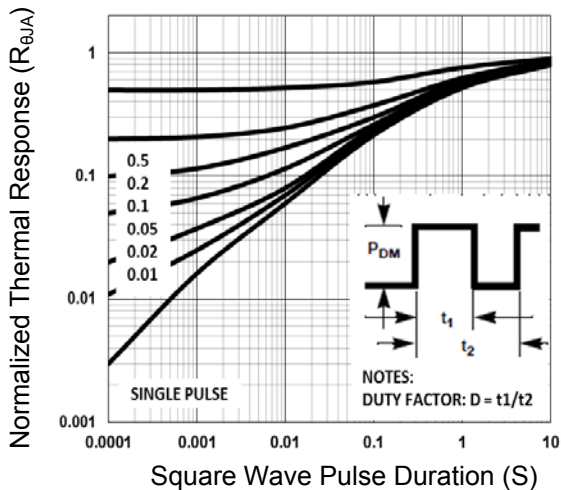
**Fig.8 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



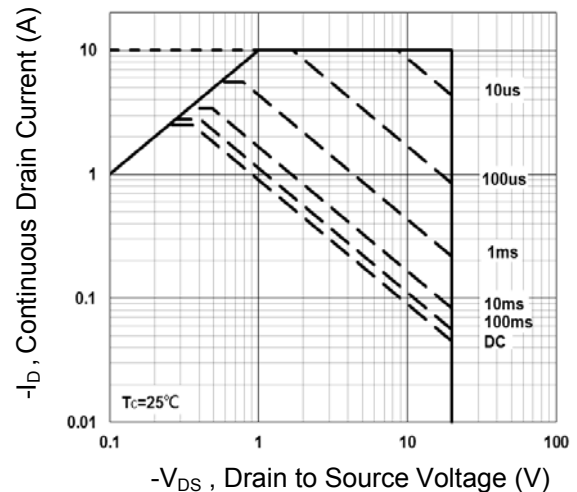
**Fig.9 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.10 Gate Charge Waveform**



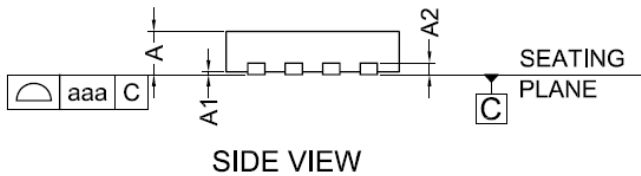
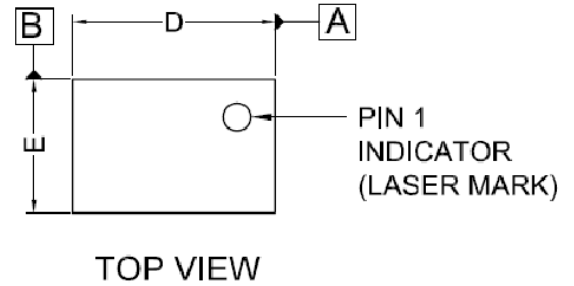
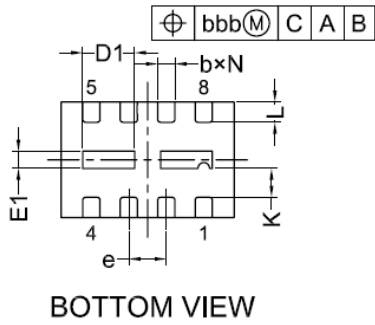
**Fig.11 Normalized Transient Impedance**



**Fig.12 Maximum Safe Operation Area**

### Package Outline Dimensions

### PPAK2X3 Dual Pin



SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.203		
b	0.25	0.30	0.35
D	2.95	3.00	3.05
D1	0.80	0.90	1.00
E	195	2.00	2.05
E1	0.20	0.30	0.40
e	0.65BSC		
L	0.30	0.35	0.40
K	0.20MIN		
N	8		
aaa	0.08		
bbb	0.10		